

A METHOD OF FORMING AN INTEGRATED CIRCUIT SUBSTRATE

ABSTRACT OF THE DISCLOSURE

5 A method of forming an integrated circuit substrate that may be adapted to
be attached to one or more electronic components. The method includes applying a
resist to a back side of a substrate which includes patterned conductive layers on a
front side and a back side of the substrate. The method further includes removing
part of the patterned conductive layer from the front side of the substrate to form
10 pads and interconnects on the front side of the substrate and applying another resist
to the front side of the substrate. The method also includes forming a pattern in
each resist that exposes the pads on the front and back sides of the substrate and
applying electrolytic nickel to the pads on the substrate.

"Express Mail" mailing label number: EV 332568621 US
Date of Deposit: June 30, 2003,

This paper or fee is being deposited on the date indicated above with
the United States Postal Service pursuant to 37 CFR 1.10, and is
addressed to the Commissioner for Patents, Mail Stop Patent
Application, P.O. Box 1450, Alexandria, VA 22313-1450.